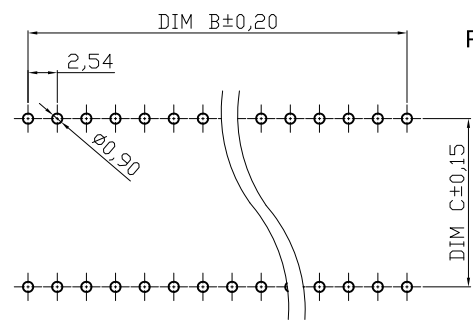
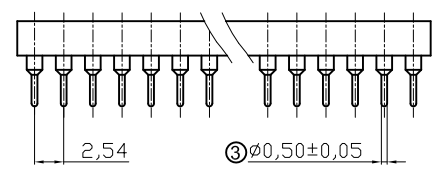
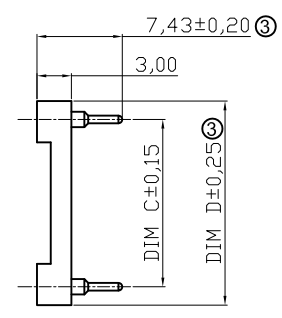
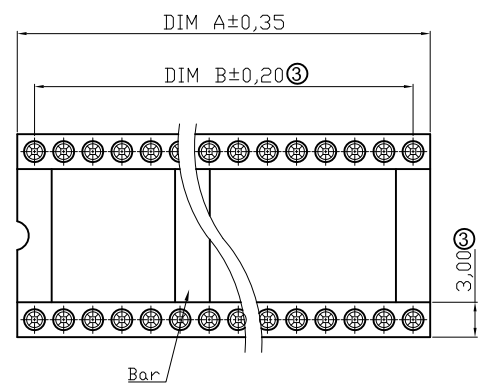


A  
B  
C  
D  
E  
F  
G  
H

A  
B  
C  
D  
E  
F  
G  
H



**NOTES:**

**MATERIAL**

- 1.Pin(outer sleeve): Brass, machined CuZn38Pb2
- ③ 2.Clip(contact 4 finger): Beryllium copper, heat treated
- 3.Plating(outer sleeve): HZL: 2um/80u"nickel, 5um/200u"Tin  
HGL: 2um/80u"nickel, Gold flash
- 4.Plating(contact): 2um/80u"nickel, Gold flash or 10u", 30u" Gold
- 5.Insulator Material: Glass filled PBT, UL94V-0 Black

**ELECTRICAL**

- 1.Current Rating: 3Amps/contact max.
- 2.Contact Resistance: 4mΩ/contact max.
- 3.Insulation Resistance: ≥10000MΩ at 500VAC
- 4.Operating Voltage: 100 VRMS/150VDC

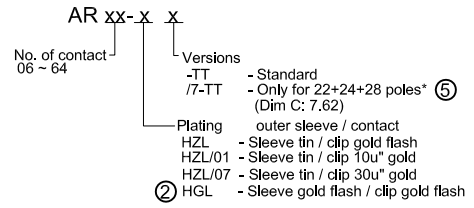
**MECHANICAL**

- 1.Average Insertion force with steel pin of  $\varnothing 0.43\text{mm}/0.017''$ : <250g
- 2.Average Withdrawal force with steel pin of  $\varnothing 0.43\text{mm}/0.017''$ : >50g min.
- 3.Mechanical life cycle: 200 min.
- 4.Operation Temperature: -40°C to +105°C
- ④ 5.Wave Soldering temperature: +245°C, 5-10s max.

Packing: Tube

Contact	Dim A	Dim B	Dim C	Dim D	Note ③
06	7.62	5.08	7.62	10.16	
08	10.16	7.62	7.62	10.16	
10	12.70	10.16	7.62	10.16	w/o bar
14	17.78	15.24	7.62	10.16	
16	20.32	17.78	7.62	10.16	
18	22.86	20.32	7.62	10.16	
20	25.40	22.86	7.62	10.16	
22*	27.94	25.40	7.62	10.16	
22	27.94	25.40	10.16	12.70	
24*	30.48	27.94	7.62	10.16	with bar
24	30.48	27.94	15.24	17.78	
28*	35.56	33.02	7.62	10.16	
28	35.56	33.02	15.24	17.78	
32	40.64	38.10	15.24	17.78	

Order Code:



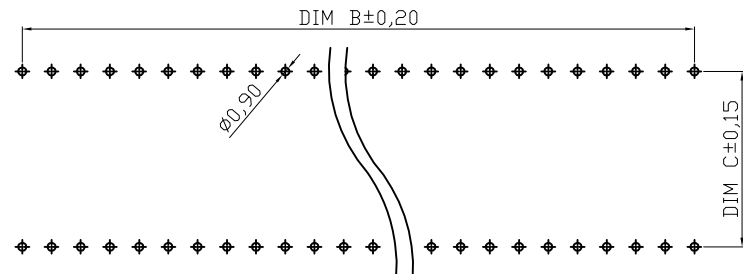
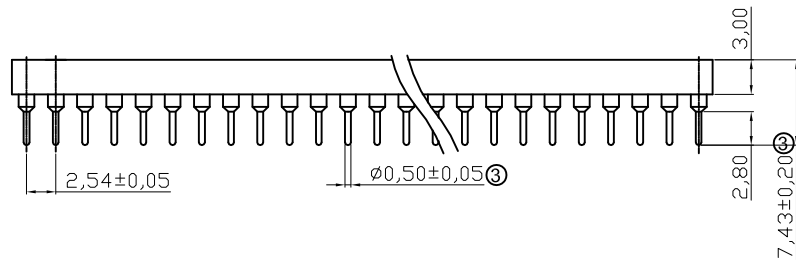
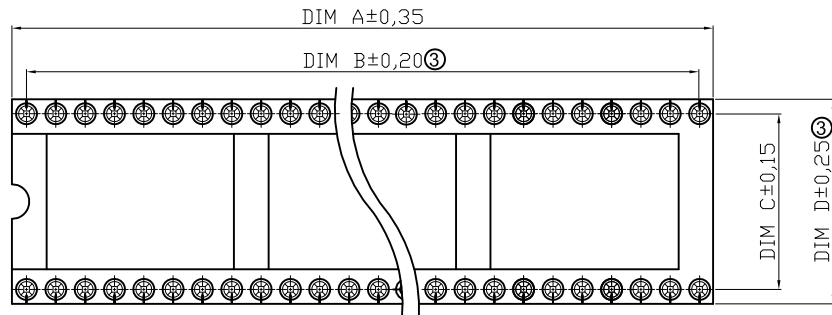
PCB LAYOUT

**RoHS compliant**  
Unit:mm

Scale	Free	⑤	Add the 22 Pin series drawing	08.08.2019	Segal		Date	Name	Customer-No.
TOLERANCE		④	Update wave solder temp.	16.08.2017	Amy	Drawn	23.07.2012	Lucas	
X.	±0.50	③	Update to new drawing	28.10.2016	Amy	Approved	08.08.2019	Amy	
X.X	±0.30	②	Add "HGL"-Version,corrected P/N code	28.01.2014	A. Plate				
X.XX	±0.20	①	Add sheet 2	16.08.2012	Lucas				
X.XXX	±0.10	①	Drawn	23.07.2012	Lucas				
DIM	TOL	①							
Angle	±5°	①							
Angle	TOL	Id.	Modification	Date	Name				



Customer-No.		AR xx-x x
ASSMANN WSW-No.		
Drawing-No.	ASS 4852 CO	rev05
Replace	Sheet	1 / 2



PCB LAYOUT

**NOTES:**

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Ø0.43mm/0.017": >50g min.
- 3.Mechanical life cycle: 200 min.
- 4.Operation Temperature: -40°C to +105°C
- ⑤ 5.Wave Soldering temperature: +245°C, 5-10s max.

Packing: Tube

Contact	Dim A	Dim B	Dim C	Dim D
36	45.72	43.18	15.24	17.78
40	50.80	48.26	15.24	17.78
42	53.34	50.80	15.24	17.78
48	60.96	58.42	15.24	17.78
50	63.50	60.96	15.24	17.78
52	66.04	63.50	15.24	17.78
50	63.50	60.96	22.86	25.40
52	66.04	63.50	22.86	25.40
64	81.28	78.74	22.86	25.40

**RoHS compliant**

Unit:mm

Scale	Free	⑤	Add the 22 Pin series drawing	08.08.2019	Segal		Date	Name	Customer-No.
<b>TOLERANCE</b>		④	Update wave solder temp.	16.08.2017	Amy	Drawn	23.07.2012	Lucas	ASSMANN WSW-No. <b>AR xx-x x</b>
X.	±0.50	③	Update to new drawing	28.10.2016	Amy	Approved	08.08.2019	Amy	
X.X	±0.30	②	Add "HGL"-Version,corrected P/N code	28.01.2014	A. Plate				
X.XX	±0.20	①	Add sheet 2	16.08.2012	Lucas				Drawing-No.
X.XXX	±0.10	①	Drawn	23.07.2012	Lucas				
DIM	TOL	①							Sheet
Angle	±5°	①							2 / 2
Angle	TOL	Id.	Modification	Date	Name				

1

2

3

4

5

6

7